

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	136	(438/116).CCLS.	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08
2	L2	2437	(438/612).CCLS.	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08
3	L3	948	(438/723).CCLS.	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08

	L #	Hits	Search Text	DBs	Time Stamp
4	L4	3518	L1 or L2 or L3	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08
5	L5	1764	L4 and (insulation or insulating or insulated)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08
6	L6	1364	L5 and (opening or via or hole)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08

	L #	Hits	Search Text	DBs	Time Stamp
7	L7	443	L6 and (solder or ball or bump)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08
8	L8	39	L7 and ((glass transparent) near substrate)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:08
9	L9	33	L8 and ((@ad<"20030224") or (@rlad<"20030224"))	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:33

	L #	Hits	Search Text	DBs	Time Stamp
10	L10	208724	((glass or transparent) near2 substrate)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:34
11	L11	10154	10 near4 (hole or via or aperture or trench or gap or space or spacing)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:35
12	L12	1097	11 same bond\$6	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:35

	L #	Hits	Search Text	DBs	Time Stamp
13	L13	100	12 same (solder or soldering or soldered or ball or paste)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 09:36

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	57	"via hole" near4 "glass substrate"	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 16:52
2	L2	3695	"glass substrate" near4 bond\$6	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 18:07
3	L3	130	2 near8 via	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 17:53

	L #	Hits	Search Text	DBs	Time Stamp
4	L4	361	"via hole" near4 glass	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 17:53
5	L5	32	4 same (bump or solder or soldering)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 17:54
6	L6	1204	(438/613).CCLS.	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 17:55

	L #	Hits	Search Text	DBs	Time Stamp
7	L7	2	4 and 6	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 17:55
8	L8	0	("2005/0009315").URPN.	USPAT	2005/03/29 18:03
9	L9	1682	melt\$6 near4 (ball or bump or solder or paste) near4 ("via hole" or hole or through-hole or gap or aperture or interconnect\$6 or plug)	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 18:06
10	L10	5911	((glass or transparent) near (substrate or wafer)) near4 bond\$6	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 18:07



	L #	Hits	Search Text	DBs	Time Stamp
11	L11	41	9 and 10	US- PGPUB; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TD B	2005/03/29 18:08